

40V Nch+Nch Power MOSFET

V _{DSS}	40V
R _{DS(on)} (Max.)	8.4mΩ
I _D	±13.5A
P _D	2.0W

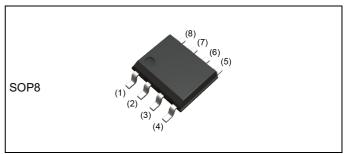
Features

- 1) Low on resistance
- 2) Small Surface Mount Package (SOP8)
- 3) Pb-free plating; RoHS compliant
- 4) Halogen Free

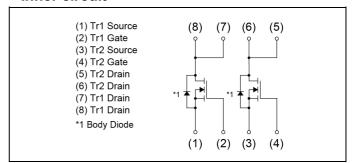
Application

Switching

Outline



•Inner circuit



Packaging specifications

	Packing	Embossed Tape					
	Reel size (mm)	330					
Туре	Tape width (mm)	12					
	Quantity (pcs)	2500					
	Taping code	TB1					
	Marking	SH8KB7					

● **Absolute maximum ratings** (T_a = 25°C ,unless otherwise specified) < Tr1 and Tr2>

Parameter	Symbol	Value	Unit
Drain - Source voltage	V _{DSS}	40	V
Continuous drain current	I _D	±13.5	Α
Pulsed drain current	I _{DP} *1	±54	Α
Gate - Source voltage	V_{GSS}	±20	V
Avalanche current, single pulse	I _{AS} *2	13.5	Α
Avalanche energy, single pulse	E _{AS} *2	17.0	mJ
Dower dissination (total)	P _D *3	2.0	\\/
Power dissipation (total)	P _D *4	1.4	W
Junction temperature	T _j	150	°C
Operating junction and storage temperature range	T _{stg}	-55 to +150	°C

●Thermal resistance

Doromotor	Cymbol	Values			l leit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal registeres innetion, embient (total)	R_{thJA}^{*3}	-	-	62.5	°C/W
Thermal resistance, junction - ambient (total)	R _{thJA} *4	-	-	89.2	C/VV

● Electrical characteristics (T_a = 25°C) < Tr1 and Tr2>

		0 186	Values			11.2	
Parameter	Symbol Conditions -		Min.	Тур.	Max.	Unit	
Drain - Source breakdown voltage	V _{(BR)DSS}	$V_{GS} = 0V$, $I_D = 1mA$	40	-	-	V	
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}}$	I _D = 1mA referenced to 25°C	-	28.9	-	mV/°C	
Zero gate voltage drain current	I _{DSS}	I _{DSS} V _{DS} = 40V, V _{GS} = 0V		-	1	μA	
Gate - Source leakage current	I _{GSS}	I_{GSS} $V_{GS} = \pm 20V$, $V_{DS} = 0V$		-	±100	nA	
Gate threshold voltage $V_{GS(th)}$ $V_{DS} = V_{GS}$		$V_{DS} = V_{GS}$, $I_D = 1mA$	1.0	-	2.5	V	
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_j}$	I _D = 1mA referenced to 25°C	-	-4.6	-	mV/°C	
Static drain - source	D *5	V _{GS} = 10V, I _D = 13.5A	-	6.5	8.4	m0	
on - state resistance	R _{DS(on)} *5	V _{GS} = 4.5V, I _D = 13.5A	-	7.5	10.5	mΩ	
Gate resistance	R_G	-	-	1.0	-	Ω	
Forward Transfer $ Y_{fs} ^{*5}$ $V_{DS} = 5V$, $I_D = 13.5A$		V _{DS} = 5V, I _D = 13.5A	13	-	-	S	

^{*1} Pw ≤ 10µs, Duty cycle ≤ 1%

^{*2} L \simeq 0.1mH, V_{DD} = 20V, R_G = 25 Ω , Starting T_j = 25 $^{\circ}$ C Fig.3-1,3-2

^{*3} Mounted on a ceramic board (30×30×0.8mm)

^{*4} Mounted on a Cu board (40×40×0.8mm)

^{*5} Pulsed

● Electrical characteristics (T_a = 25°C) < Tr1 and Tr2>

Darameter	Cumbal	Conditions	Values			Unit	
Parameter	Symbol Conditions –		Min.	Тур.	Max.	Unit	
Input capacitance	C _{iss}	V _{GS} = 0V	-	1570	-		
Output capacitance	C _{oss}	V _{DS} = 20V	-	800	-	pF	
Reverse transfer capacitance	C _{rss}	f = 1MHz	1	75	-		
Turn - on delay time	t _{d(on)} *5	V _{DD} ≈ 20V,V _{GS} = 10V	-	18	-		
Rise time	t _r *5	I _D = 6.75A	-	16	-		
Turn - off delay time	t _{d(off)} *5	$R_L = 2.96\Omega$	-	47	-	ns	
Fall time	t _f *5	$R_G = 10\Omega$	-	18	-		

● Gate charge characteristics (T_a = 25°C) < Tr1 and Tr2>

Darameter	Cumbal	Conditions		Values			1 1:4	
Parameter	Symbol			Min.	Тур.	Max.	Unit	
Total mate above	O *5		V _{GS} = 10V	-	27.0	-		
Total gate charge	Q_g^{*5}	V _{DD} ≃ 20V		-	13.0	-	0	
Gate - Source charge	Q _{gs} *5	I _D = 13.5A	V _{GS} = 4.5V	-	4.3	-	nC	
Gate - Drain charge	Q _{gd} *5				-	4.7	-	

● Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

<Tr1 and Tr2>

Parameter	Symbol	Conditions	Values			Unit	
Farameter	Symbol	Conditions	Min.	Тур.	Max.	Offic	
Continuous forward current	I _S	T _a = 25°C	-	-	1.67	^	
Pulse forward current	I _{SP} *1	1 _a – 25 C	-	-	54	A	
Forward voltage	V _{SD} *5	V _{GS} = 0V, I _S = 1.67A	-	-	1.2	V	
Reverse recovery time	t _{rr} *5	I _S = 13.5A, V _{GS} = 0V	-	39	-	ns	
Reverse recovery charge	Q _{rr} *5	di/dt = 100A/μs	-	49	-	nC	

Fig.1 Power Dissipation Derating Curve

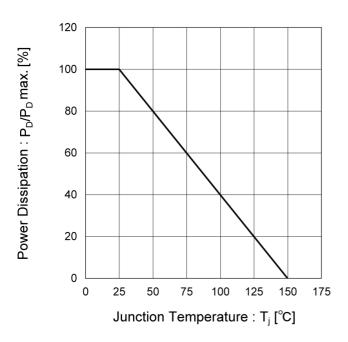
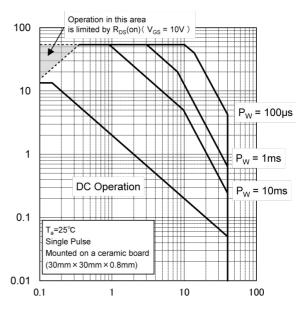


Fig.2 Maximum Safe Operating Area



Drain Current : I_D [A]

Drain - Source Voltage: V_{DS}[V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

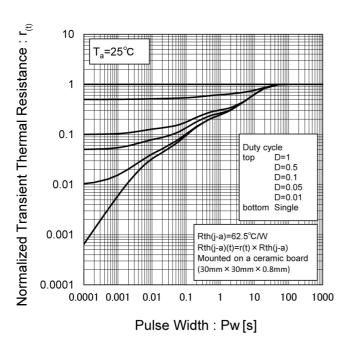


Fig.4 Single Pulse Maximum Power Dissipation

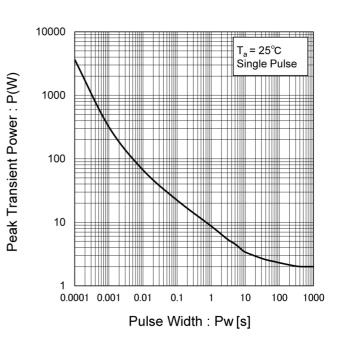


Fig.5 Typical Output Characteristics(I)

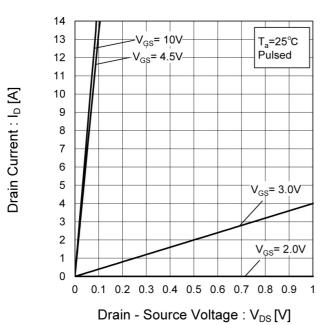
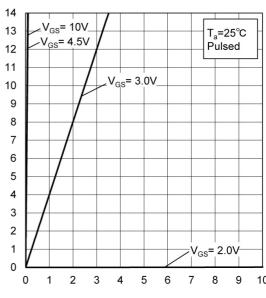


Fig.6 Typical Output Characteristics(II)



Drain Current : I_D [A]

Drain - Source Voltage : V_{DS} [V]

Fig.7 Breakdown Voltage vs.
Junction Temperature

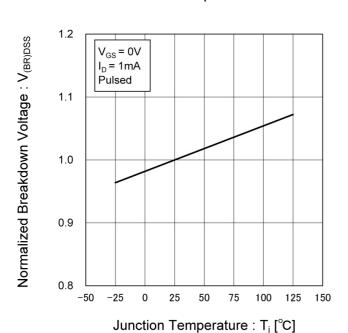


Fig.8 Typical Transfer Characteristics

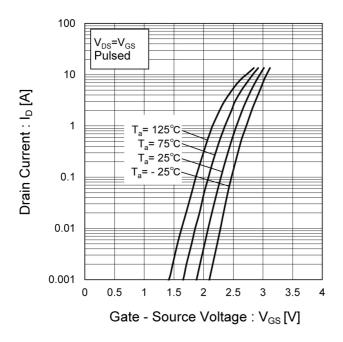


Fig.9 Gate Threshold Voltage vs.
Junction Temperature

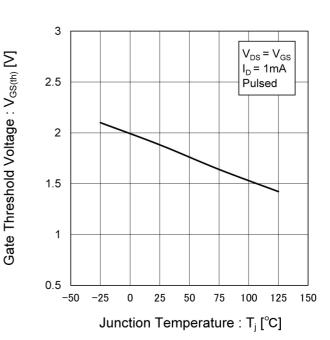


Fig.10 Forward Transfer Admittance vs.
Drain Current

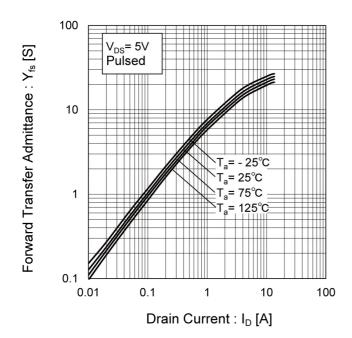


Fig.11 Drain Current Derating Curve

120 100 Drain Current Dissipation 80 : I_D/I_Dmax. [%] 60 40 20 0 -25 0 25 50 75 100 125 150 Junction Temperature : T_j [°C]

Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

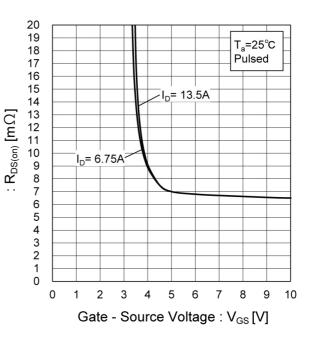
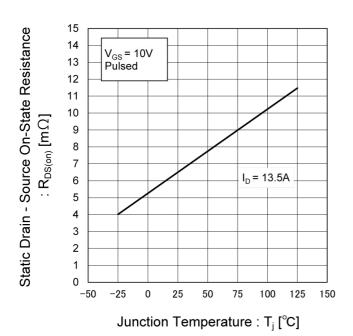


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature



Static Drain - Source On-State Resistance

Fig.14 Static Drain - Source On - State Resistance vs. Drain Current (I)

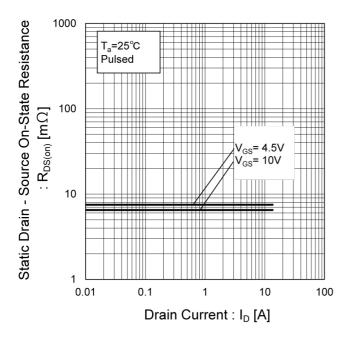


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)

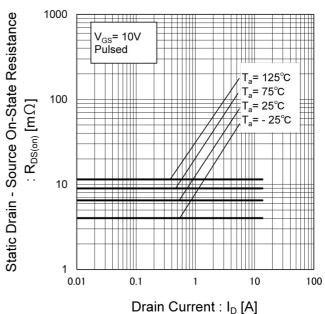


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III)

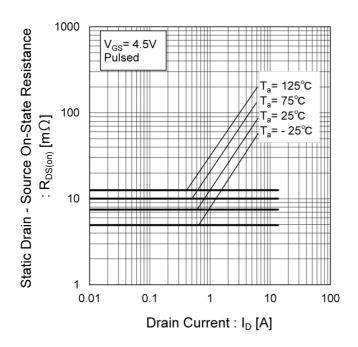


Fig.17 Typical Capacitances vs.

Drain - Source Voltage

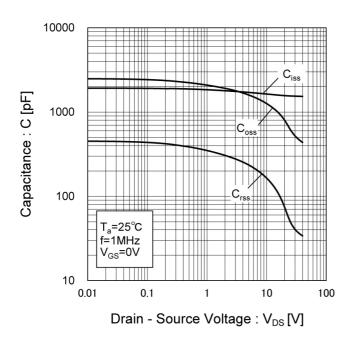


Fig.18 Switching Characteristics

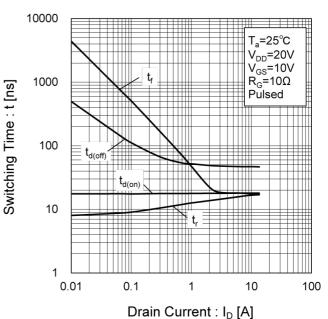


Fig.19 Typical Gate Charge

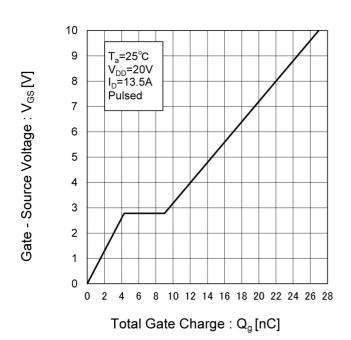
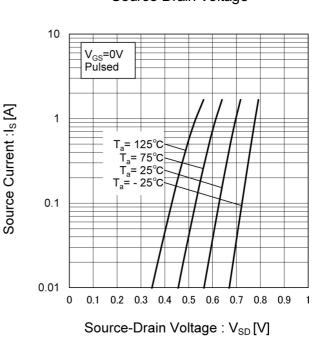


Fig.20 Source Current vs.

Source Drain Voltage



• Measurement circuits < It is the same for the Tr1 and Tr2>

Fig.1-1 Switching Time Measurement Circuit

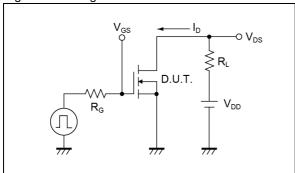


Fig.2-1 Gate Charge Measurement Circuit

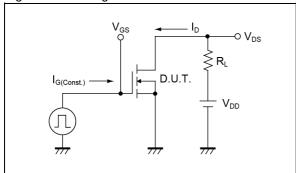


Fig.3-1 Avalanche Measurement Circuit

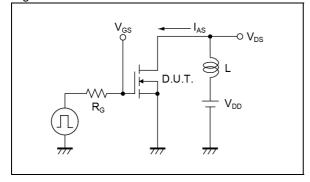


Fig.1-2 Switching Waveforms

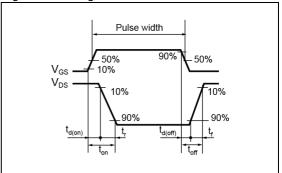


Fig.2-2 Gate Charge Waveform

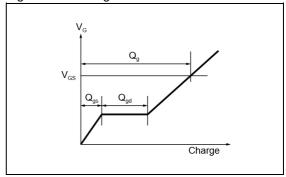
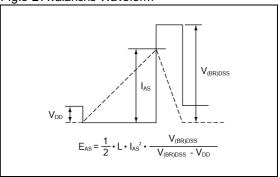
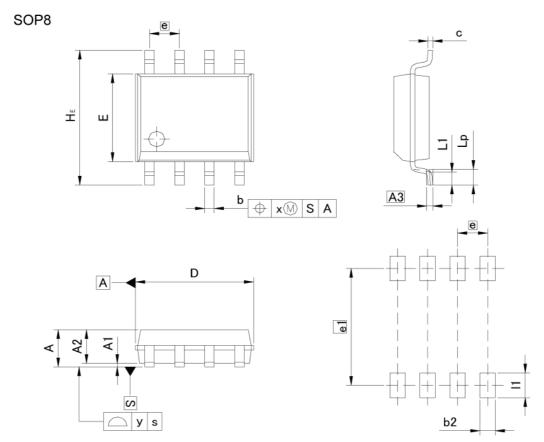


Fig.3-2 Avalanche Waveform



Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIM	ETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	-	1.75	-	0.069	
A1	0.	15	0.0	06	
A2	1.40	1.60	0.055	0.063	
A3	0.3	25	0.0	10	
b	0.30	0.50	0.012	0.020	
С	0.10	0.30	0.004	0.012	
D	4.80	5.20	0.189	0.205	
E	3.75	4.05	0.148	0.159	
е	1.3	27	0.050		
HE	5.70	6.30	0.224	0.248	
L1	0.40	0.60	0.016	0.024	
Lp	0.65	0.85	0.026	0.033	
х	0.	15	0.0	06	
у	0.10		y 0.10 0.004		04
DIM	MILIM	ETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	

DIM	MILIMETERS		INCHES		
DIM	MIN	MAX	MIN	MAX	
b2	-	0.65	-	0.026	
e1	5.	15	0.2	03	
I1	-,:	1.15	- 1	0.045	

Dimension in mm/inches



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CLASSIV	CLASSⅢ	CLASSⅢ	CLASSⅢ

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 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
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- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
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- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
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